

# 2MBI300VH-120-50

IGBT Modules

## IGBT MODULE (V series) 1200V / 300A / 2 in one package

### ■ Features

- High speed switching
- Voltage drive
- Low Inductance module structure

### ■ Applications

- Inverter for Motor Drive
- AC and DC Servo Drive Amplifier
- Uninterruptible Power Supply
- Industrial machines, such as Welding machines

### ■ Maximum Ratings and Characteristics

#### ● Absolute Maximum Ratings (at Tc=25°C unless otherwise specified)

Absolute Maximum Ratings (at TA = 25 °C unless otherwise specified)						
Items		Symbols	Conditions	Maximum ratings	Units	
Inverter	Collector-Emitter voltage	V <sub>CE</sub>			1200	V
	Gate-Emitter voltage	V <sub>GE</sub>			±20	V
	Collector current	I <sub>c</sub>	Continuous	T <sub>c</sub> =100°C	300	A
				T <sub>c</sub> =25°C	360	
		I <sub>c</sub> pulse	1ms		600	
		-I <sub>c</sub>			300	
		-I <sub>c</sub> pulse	1ms		600	
	Collector power dissipation	P <sub>c</sub>	1 device		1600	W
Junction temperature	T <sub>j</sub>			175	°C	
Operating junction temperature (under switching conditions)	T <sub>jop</sub>			150		
Case temperature	T <sub>c</sub>			125		
Storage temperature	T <sub>stg</sub>			-40 ~ +125		
Isolation voltage	between terminal and copper base (*1)	V <sub>iso</sub>	AC : 1min.	2500	VAC	
Screw torque	Mounting (*2)	-		6.0	N m	
	Terminals (*3)	-		5.0		

Note \*1: All terminals should be connected together during the test.

Note \*2: Recommendable Value : 3.0-6.0 Nm (M5 or M6)

Note \*3: Recommendable Value : 2.5-5.0 Nm (M6)

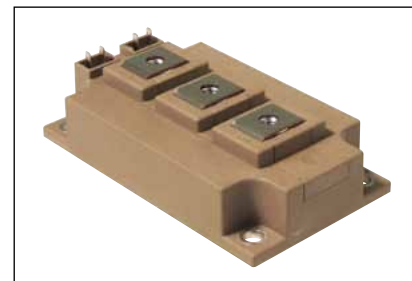
#### ● Electrical characteristics (at Tj= 25°C unless otherwise specified)

Items			Symbols	Conditions	Characteristics			Units	
					min.	typ.	max.		
Inverter	Zero gate voltage collector current		I <sub>CE</sub>	V <sub>GE</sub> = 0V, V <sub>CE</sub> = 1200V		-	-	2.0	mA
	Gate-Emitter leakage current		I <sub>GES</sub>	V <sub>CE</sub> = 0V, V <sub>GE</sub> = ±20V		-	-	400	nA
	Gate-Emitter threshold voltage		V <sub>GE (th)</sub>	V <sub>CE</sub> = 20V, I <sub>C</sub> = 300mA		6.0	6.5	7.0	V
	Collector-Emitter saturation voltage		V <sub>CE (sat)</sub> (terminal)	V <sub>GE</sub> = 15V I <sub>C</sub> = 300A	T <sub>J</sub> =25°C	-	1.95	2.40	V
					T <sub>J</sub> =125°C	-	2.25	-	
			T <sub>J</sub> =150°C		-	2.30	-		
			T <sub>J</sub> =25°C		-	1.75	2.10		
			T <sub>J</sub> =125°C		-	2.05	-		
			T <sub>J</sub> =150°C		-	2.10	-		
	Internal gate resistance		R <sub>g(int)</sub>	-		-	2.5	-	Ω
	Input capacitance		C <sub>ies</sub>	V <sub>CE</sub> = 10V, V <sub>GE</sub> = 0V, f = 1MHz		-	24.1	-	nF
	Turn-on time		t <sub>on</sub>	V <sub>CC</sub> = 600V    L <sub>S</sub> = 30nH		-	0.60	-	μsec
			t <sub>r</sub>	I <sub>C</sub> = 300A		-	0.20	-	
			t <sub>r (i)</sub>	V <sub>GE</sub> = ±15V		-	0.05	-	
	Turn-off time		t <sub>off</sub>	R <sub>G</sub> = 1.8Ω		-	0.80	-	μsec
			t <sub>f</sub>	T <sub>J</sub> = 150°C		-	0.08	-	
Forward on voltage		V <sub>F</sub> (terminal)	V <sub>GE</sub> = 0V I <sub>F</sub> = 300A	T <sub>J</sub> =25°C	-	1.90	2.35	V	
				T <sub>J</sub> =125°C	-	2.05	-		
				T <sub>J</sub> =150°C	-	2.00	-		
		V <sub>F</sub> (chip)		T <sub>J</sub> =25°C	-	1.70	2.15		
				T <sub>J</sub> =125°C	-	1.85	-		
Reverse recovery time		t <sub>rr</sub>	I <sub>F</sub> = 300A		-	0.15	-	μsec	

#### ● Thermal resistance characteristics

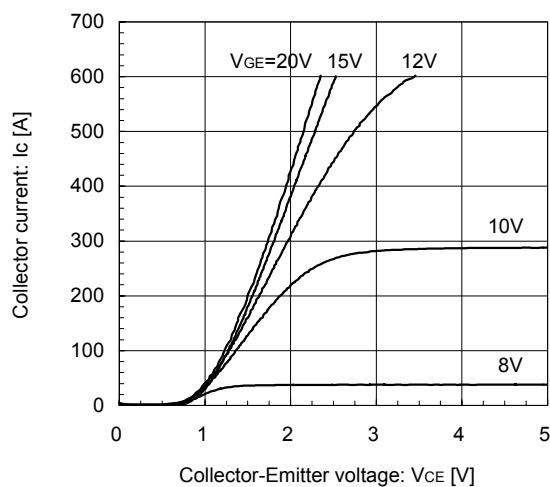
Items	Symbols	Conditions	Characteristics			Units
			min.	typ.	max.	
Thermal resistance (1device)	R <sub>th(j-c)</sub>	IGBT	-	-	0.093	°C/W
		FWD	-	-	0.150	
Contact thermal resistance (1device) (*4)	R <sub>th(c-f)</sub>	with Thermal Compound	-	0.0125	-	

Note \*4: This is the value which is defined mounting on the additional cooling fin with thermal compound.

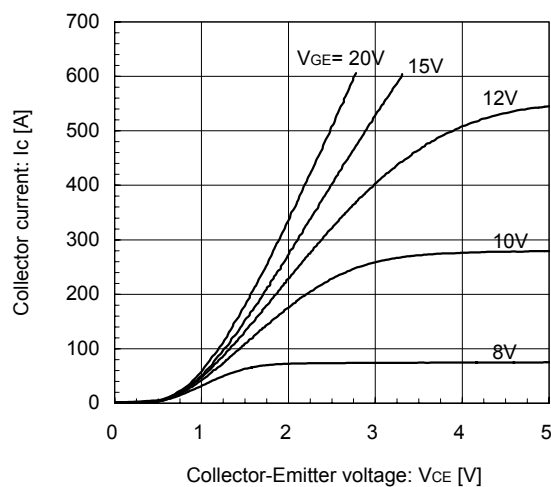


## ■ Characteristics (Representative)

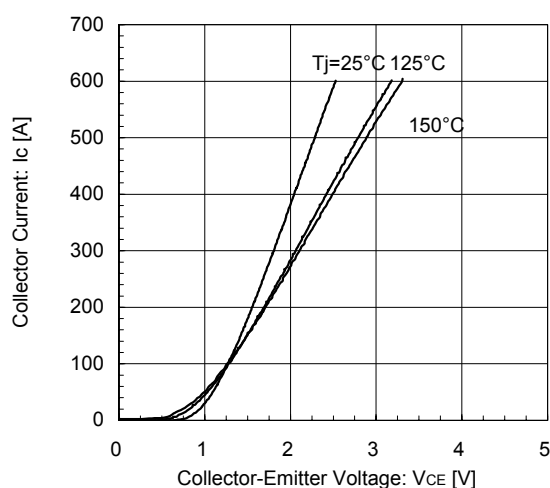
Collector current vs. Collector-Emitter voltage (typ.)  
T<sub>j</sub> = 25°C / chip



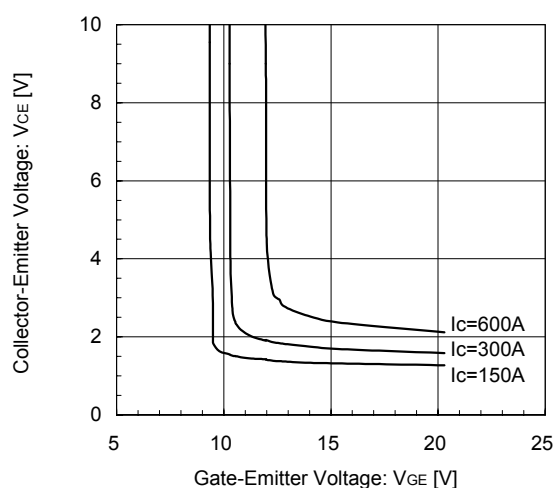
Collector current vs. Collector-Emitter voltage (typ.)  
T<sub>j</sub> = 150°C / chip



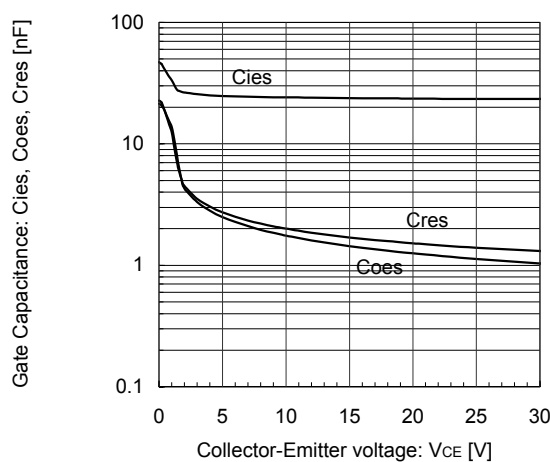
Collector current vs. Collector-Emitter voltage (typ.)  
V<sub>GE</sub> = 15V / chip



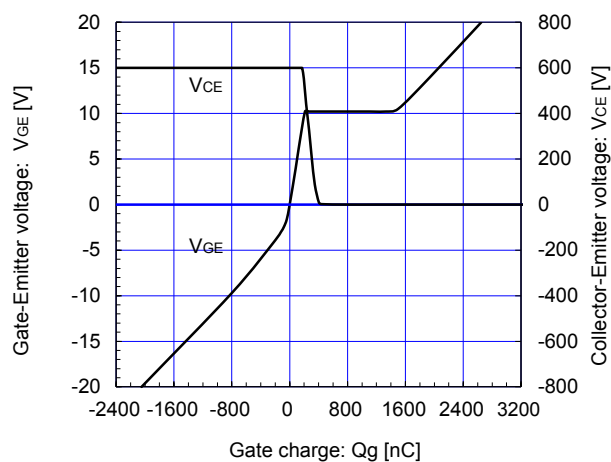
Collector-Emitter voltage vs. Gate-Emitter voltage (typ.)  
T<sub>j</sub> = 25°C / chip



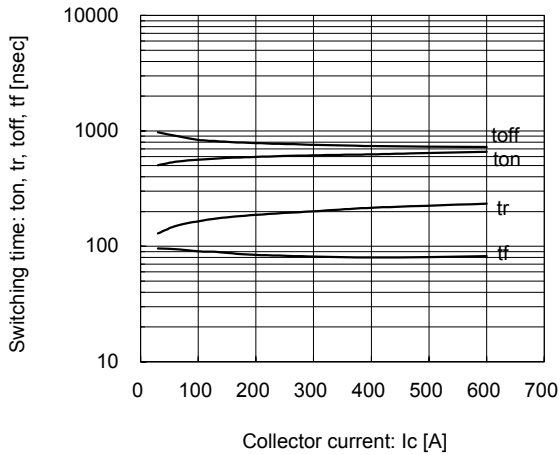
Gate Capacitance vs. Collector-Emitter Voltage (typ.)  
V<sub>GE</sub> = 0V, f = 1MHz, T<sub>j</sub> = 25°C



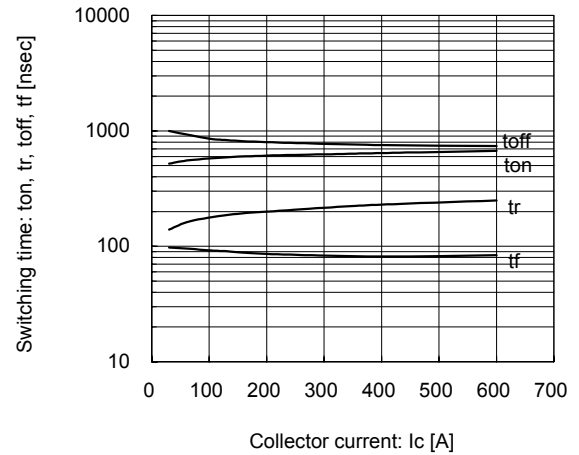
Dynamic Gate Charge (typ.)  
V<sub>cc</sub> = 600V, I<sub>c</sub> = 300A, T<sub>j</sub> = 25°C



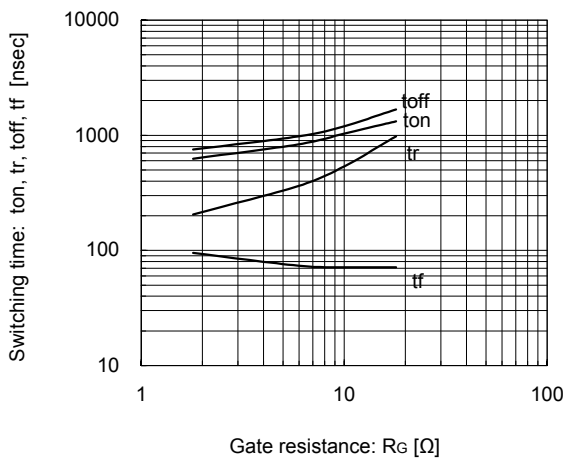
Switching time vs. Collector current (typ.)  
 $V_{CC}=600V$ ,  $V_{GE}=\pm 15V$ ,  $R_G=1.8\Omega$ ,  $T_J=125^\circ C$



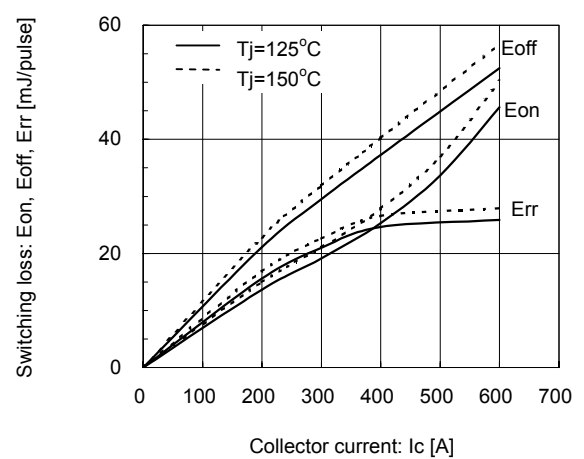
Switching time vs. Collector current (typ.)  
 $V_{CC}=600V$ ,  $V_{GE}=\pm 15V$ ,  $R_G=1.8\Omega$ ,  $T_J=150^\circ C$



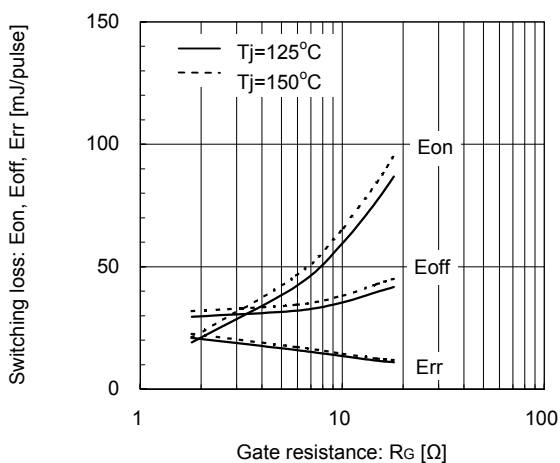
Switching time vs. Gate resistance (typ.)  
 $V_{CC}=600V$ ,  $I_C=300A$ ,  $V_{GE}=\pm 15V$ ,  $T_J=125^\circ C$



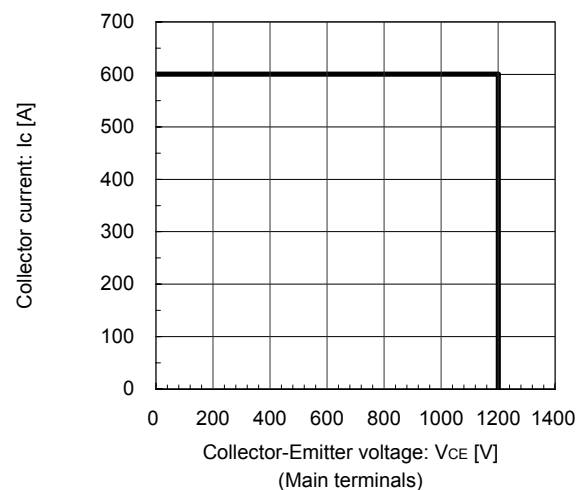
Switching loss vs. Collector current (typ.)  
 $V_{CC}=600V$ ,  $V_{GE}=\pm 15V$ ,  $R_G=1.8\Omega$ ,  $T_J=125^\circ C$ ,  $150^\circ C$



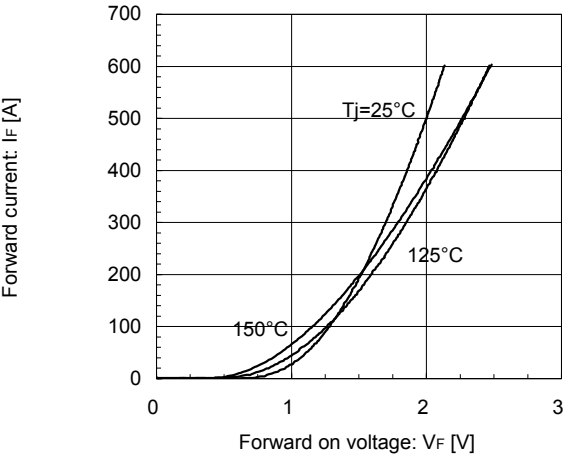
Switching loss vs. Gate resistance (typ.)  
 $V_{CC}=600V$ ,  $I_C=300A$ ,  $V_{GE}=\pm 15V$ ,  $T_J=125^\circ C$ ,  $150^\circ C$



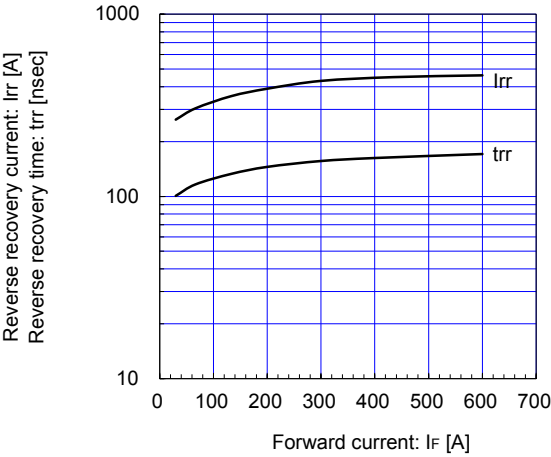
Reverse bias safe operating area (max.)  
 $+V_{GE}=15V$ ,  $-V_{GE}=15V$ ,  $R_G=1.8\Omega$ ,  $T_J=150^\circ C$



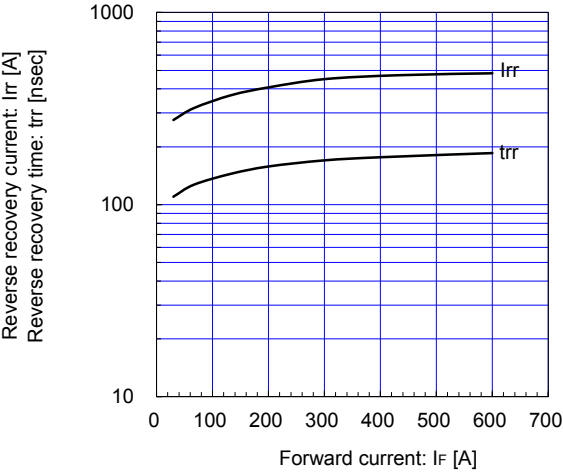
Forward Current vs. Forward Voltage (typ.)  
chip



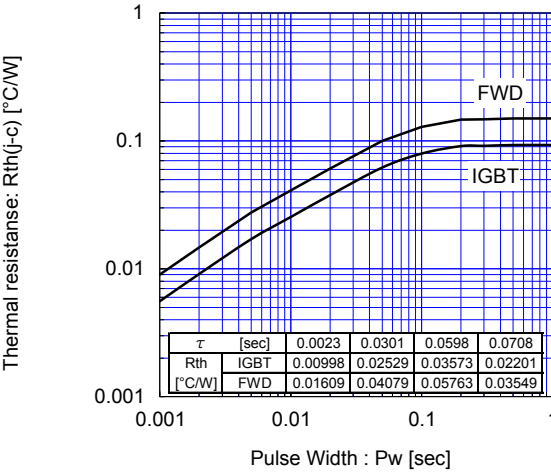
Reverse Recovery Characteristics (typ.)  
 $V_{CC}=600\text{V}$ ,  $V_{GE}=\pm 15\text{V}$ ,  $R_G=1.8\Omega$ ,  $T_j=125^{\circ}\text{C}$



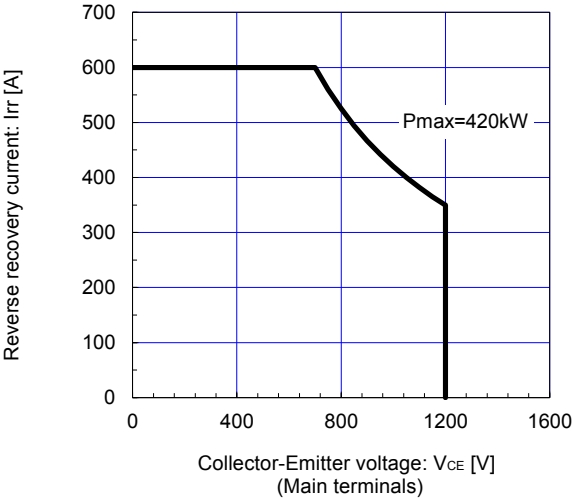
Reverse Recovery Characteristics (typ.)  
 $V_{CC}=600\text{V}$ ,  $V_{GE}=\pm 15\text{V}$ ,  $R_G=1.8\Omega$ ,  $T_j=150^{\circ}\text{C}$



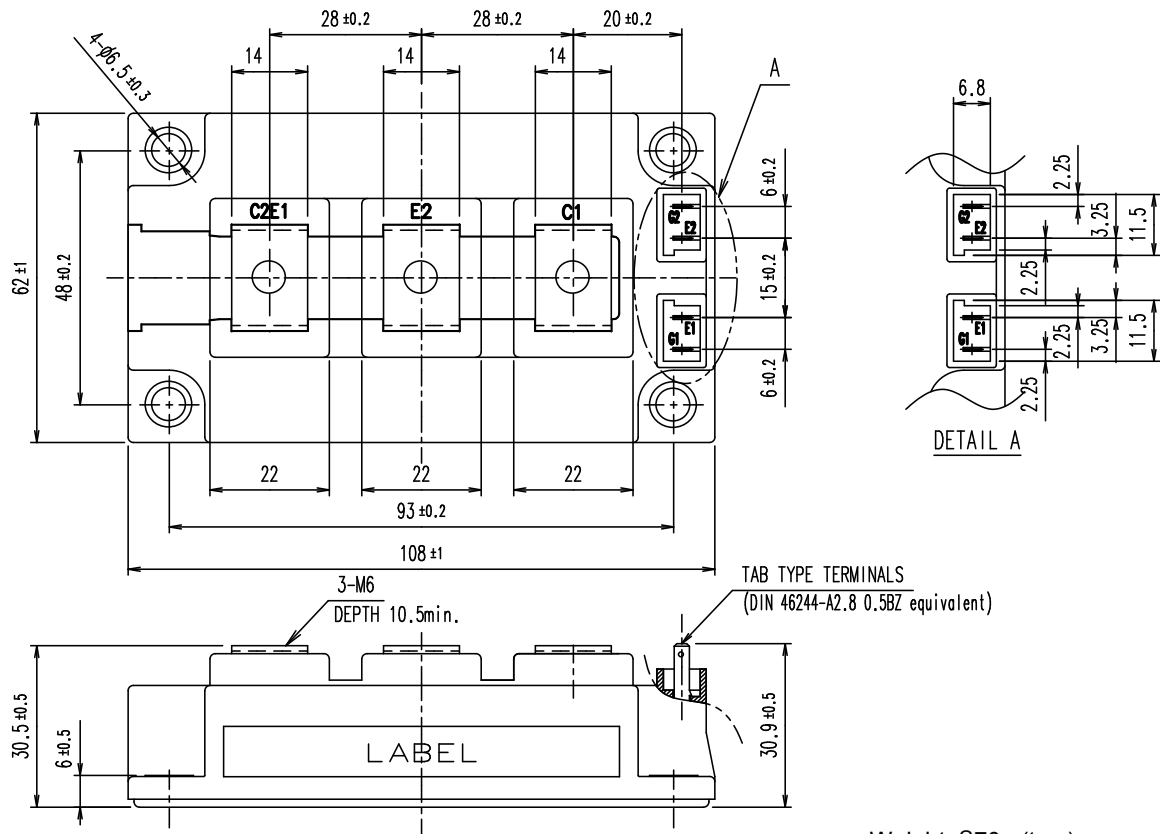
Transient Thermal Resistance (max.)



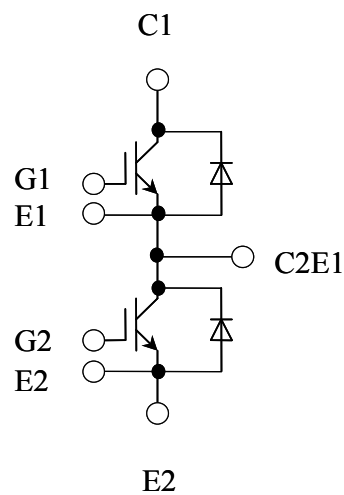
FWD safe operating area (max.)  
 $T_j=150^{\circ}\text{C}$



### ■ Outline Drawings (Unit: mm)



### ■ Equivalent Circuit



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• Medical equipment	
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• Submarine repeater equipment		
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